

OSG60R2K2x_Datasheet



Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Extremely low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

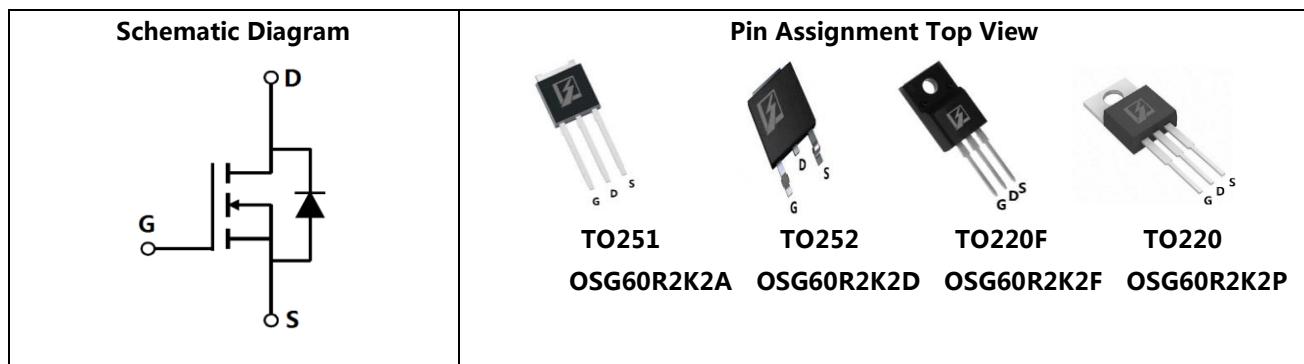
- ◆ Lighting
- ◆ Hard switching PWM
- ◆ Server power supply
- ◆ Charger

■ General Description

OSG60R2K2x use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device is suitable for active power factor correction and switching mode power supply applications.

◆ V_{DS} , min@ T_{jmax}	650 V
◆ I_D , pulse	6 A
◆ $R_{DS(ON)}$, max @ $V_{GS}=10$ V	2.2 Ω
◆ Q_g	5.1 nC

■ Schematic and Package Information



■ Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾	I_D	2	A
Continuous drain current ¹⁾ $T_j=100$ °C		1.25	
Pulsed drain current ²⁾	I_D , pulse	6	A
Power dissipation ³⁾ for TO251, TO252, TO220	P_D	18	W
Power dissipation ³⁾ for TO220F		20	
Single pulsed avalanche energy ⁵⁾	E_{AS}	60	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0...480$ V	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0...480$ V, $I_{SD} \leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg} , T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value		Unit
		TO251/TO252/TO220	TO220F	
Thermal resistance, junction-case	R _{θJC}	6.3	6.9	°C/W
Thermal resistance, junction-ambient ⁴⁾	R _{θJA}	62	62.5	°C/W

■ Electrical Characteristics at T_j=25 °C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV _{DSS}	600			V	V _{GS} =0 V, I _D =250 μA
		650	750			V _{GS} =0 V, I _D =250 μA T _j =150 °C
Gate threshold voltage	V _{GS(th)}	2.0		4.0	V	V _{DS} =V _{GS} , I _D =250 μA
Drain-source on-state resistance	R _{DS(ON)}		1.9	2.2	Ω	V _{GS} =10 V, I _D =1 A
			4.8			V _{GS} =10 V, I _D =1 A, T _j =150 °C
Gate-source leakage current	I _{GSS}			100	nA	V _{GS} =30 V
				-100		V _{GS} =-30 V
Drain-source leakage current	I _{DSS}			1	μA	V _{DS} =600 V, V _{GS} =0 V

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		118		pF	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		12.5		pF	
Reverse transfer capacitance	C _{rss}		0.76		pF	
Turn-on delay time	t _{d(on)}		50.4		ns	V _{GS} =10 V, V _{DS} =380 V, R _G =25 Ω, I _D =2 A
Rise time	t _r		23.9		ns	
Turn-off delay time	t _{d(off)}		103.1		ns	
Fall time	t _f		44.7		ns	



■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		5.1		nC	$I_D=2\text{ A}$, $V_{DS}=480\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		1		nC	
Gate-drain charge	Q_{gd}		2.3		nC	
Gate plateau voltage	$V_{plateau}$		5.4		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			2	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			6		
Diode forward voltage	V_{SD}			1.4	V	$I_S=2\text{ A}, V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		153.9		ns	$V_R=400\text{ V}, I_S=2\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		0.617		μC	
Peak reverse recovery current	I_{rrm}		8.7		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=50\text{ V}$, $R_G=25\text{ }\Omega$, $L=20\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.



■ Electrical Characteristics Diagrams

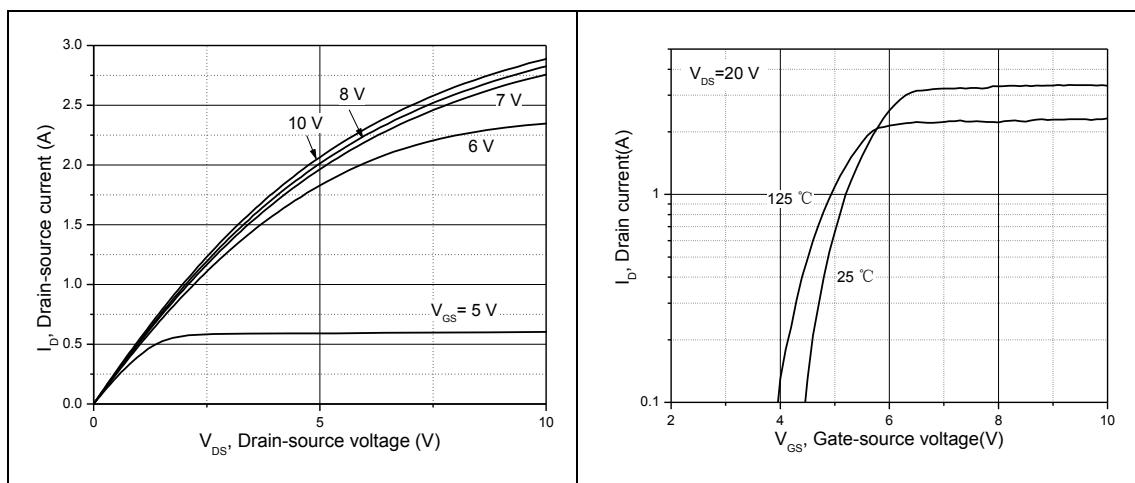


Figure 1, Typ. output characteristics

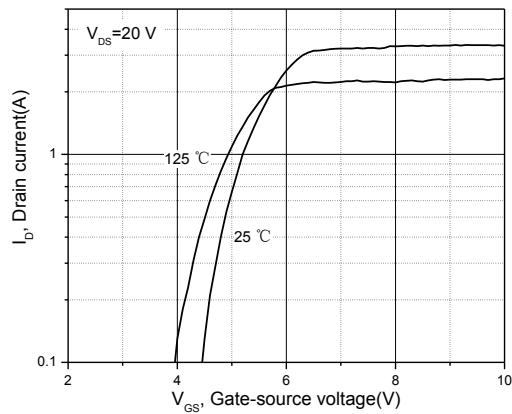


Figure 2, Typ. transfer characteristics

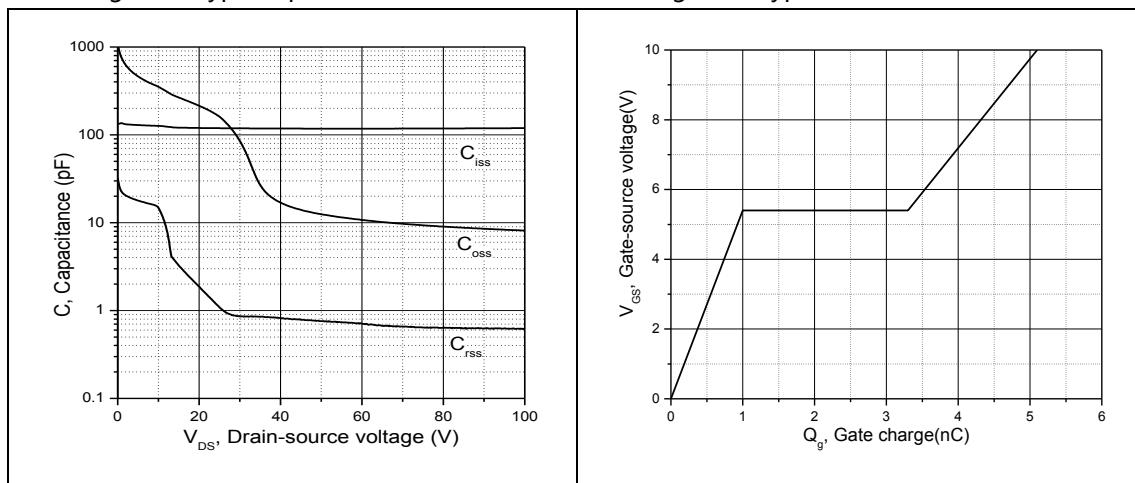


Figure 3, Typ. capacitances

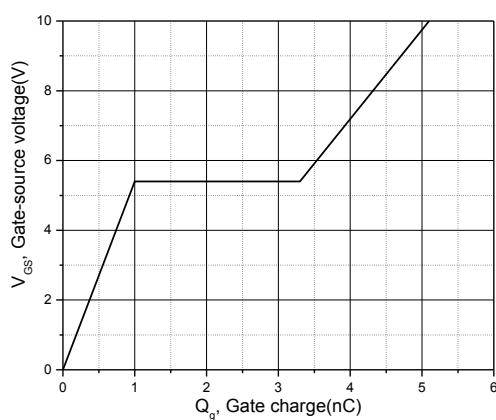


Figure 4, Typ. gate charge

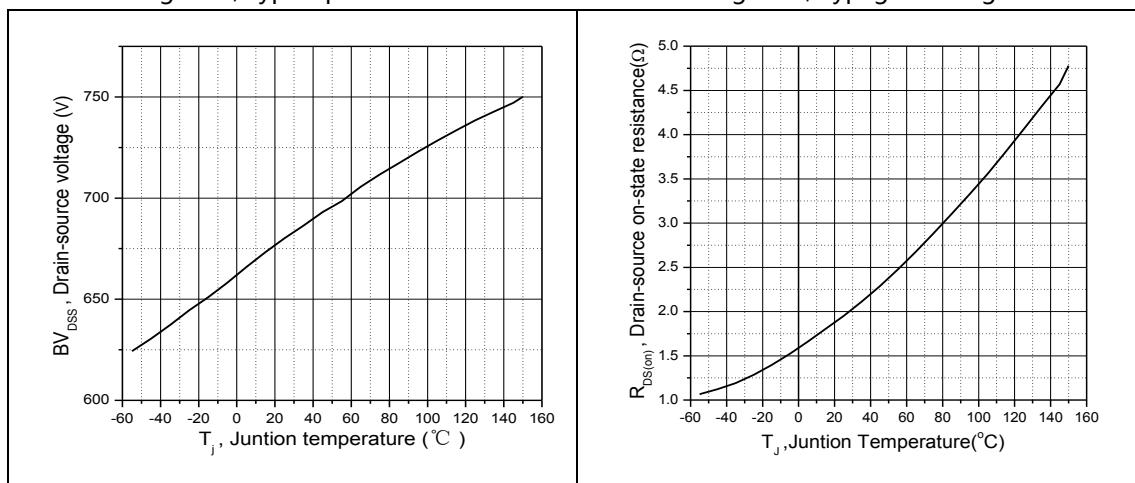


Figure 5, Drain-source breakdown voltage

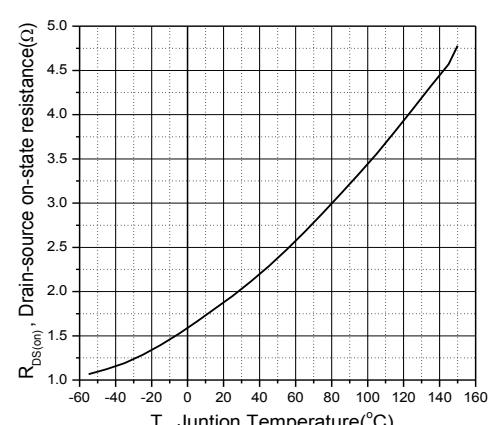


Figure 6, Drain-source on-state resistance

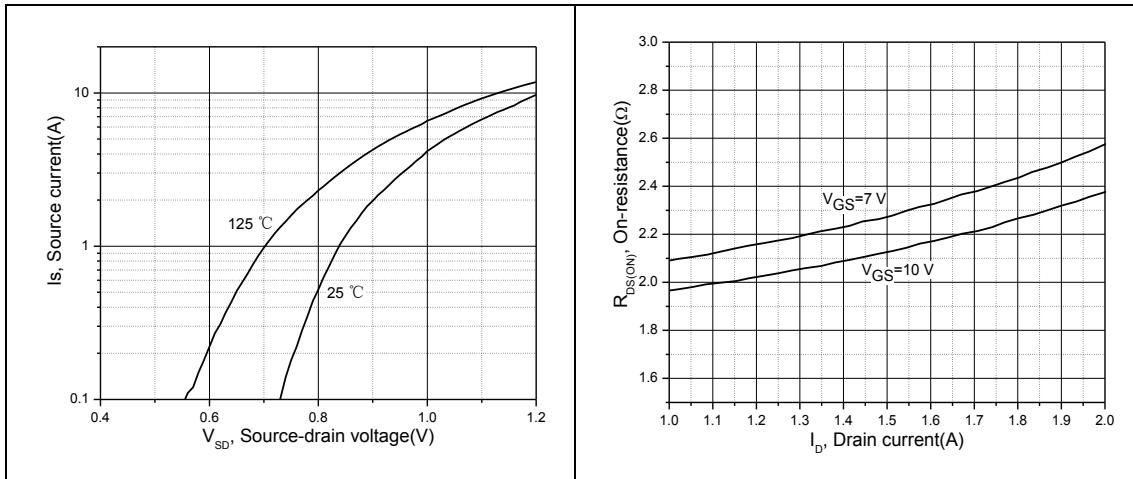


Figure 7, Forward characteristic of body diode

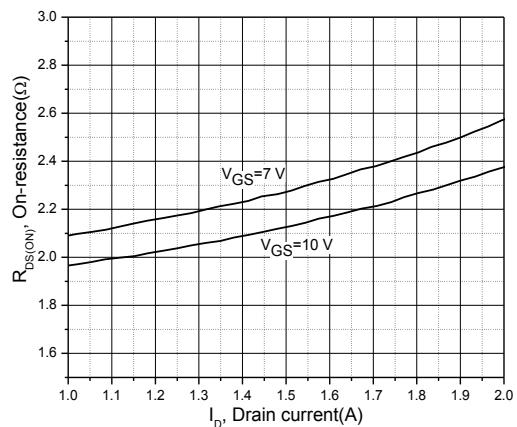


Figure 8, Drain-source on-state resistance

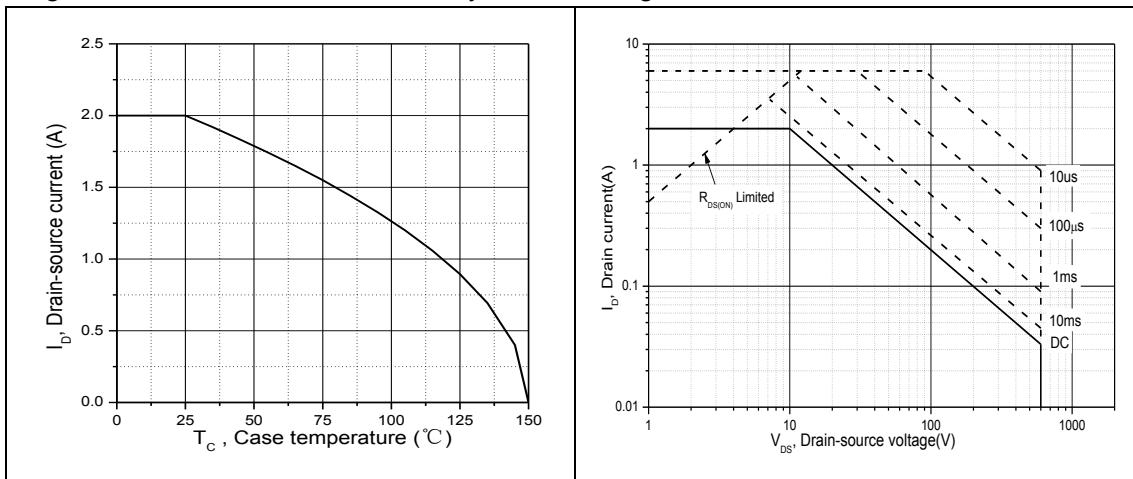
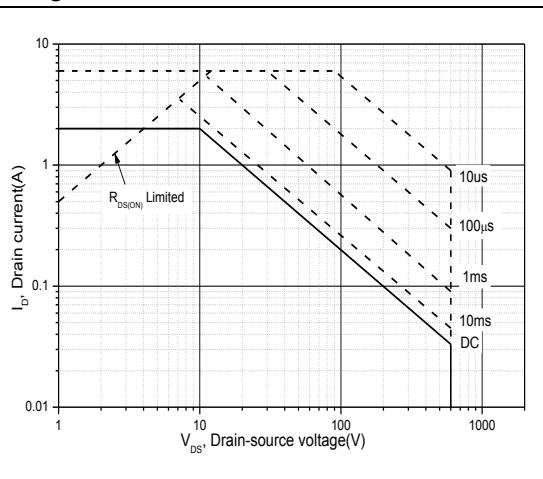
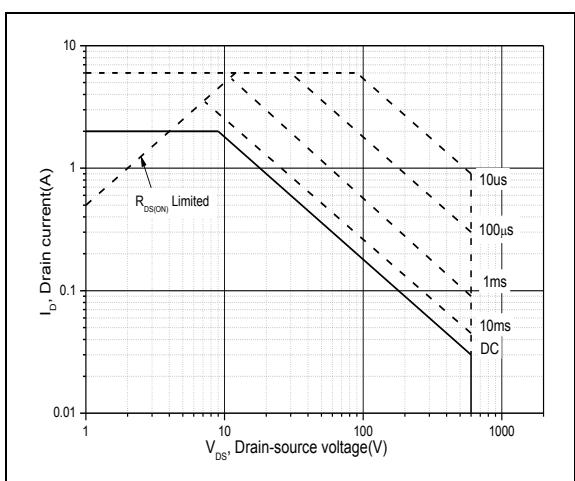


Figure 9, Drain current

Figure 10, Safe operation area for
TO251/TO252/TO220 $T_C = 25^\circ\text{C}$ Figure 11, Safe operation area for TO220
 $T_C = 25^\circ\text{C}$



■ Test circuits and waveforms

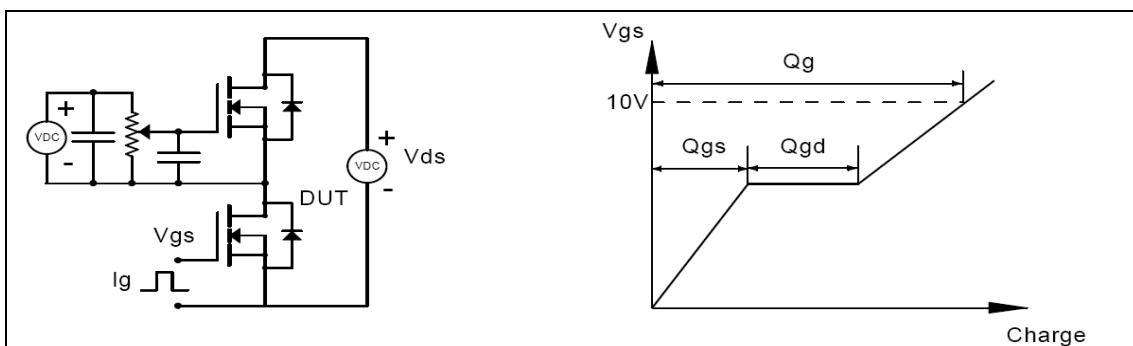


Figure 1, Gate charge test circuit & waveform

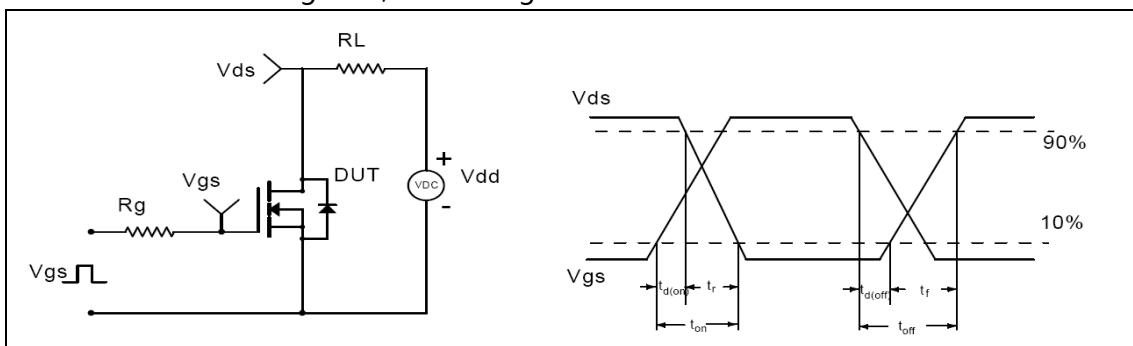


Figure 2, Switching time test circuit & waveforms

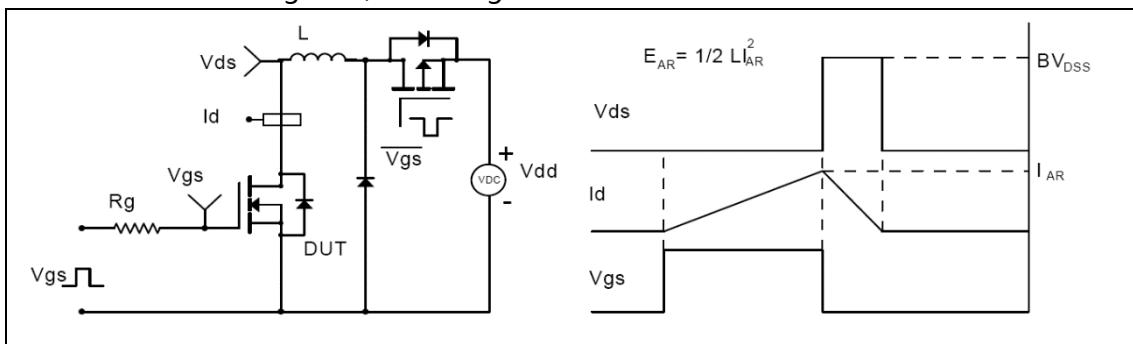


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

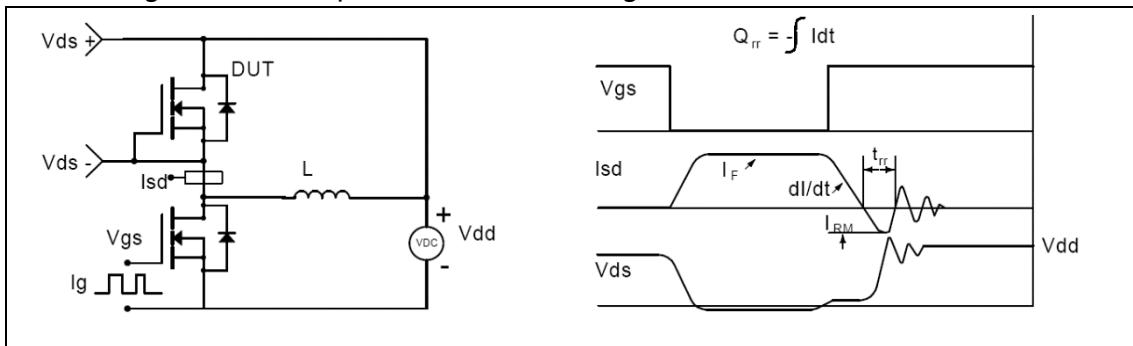
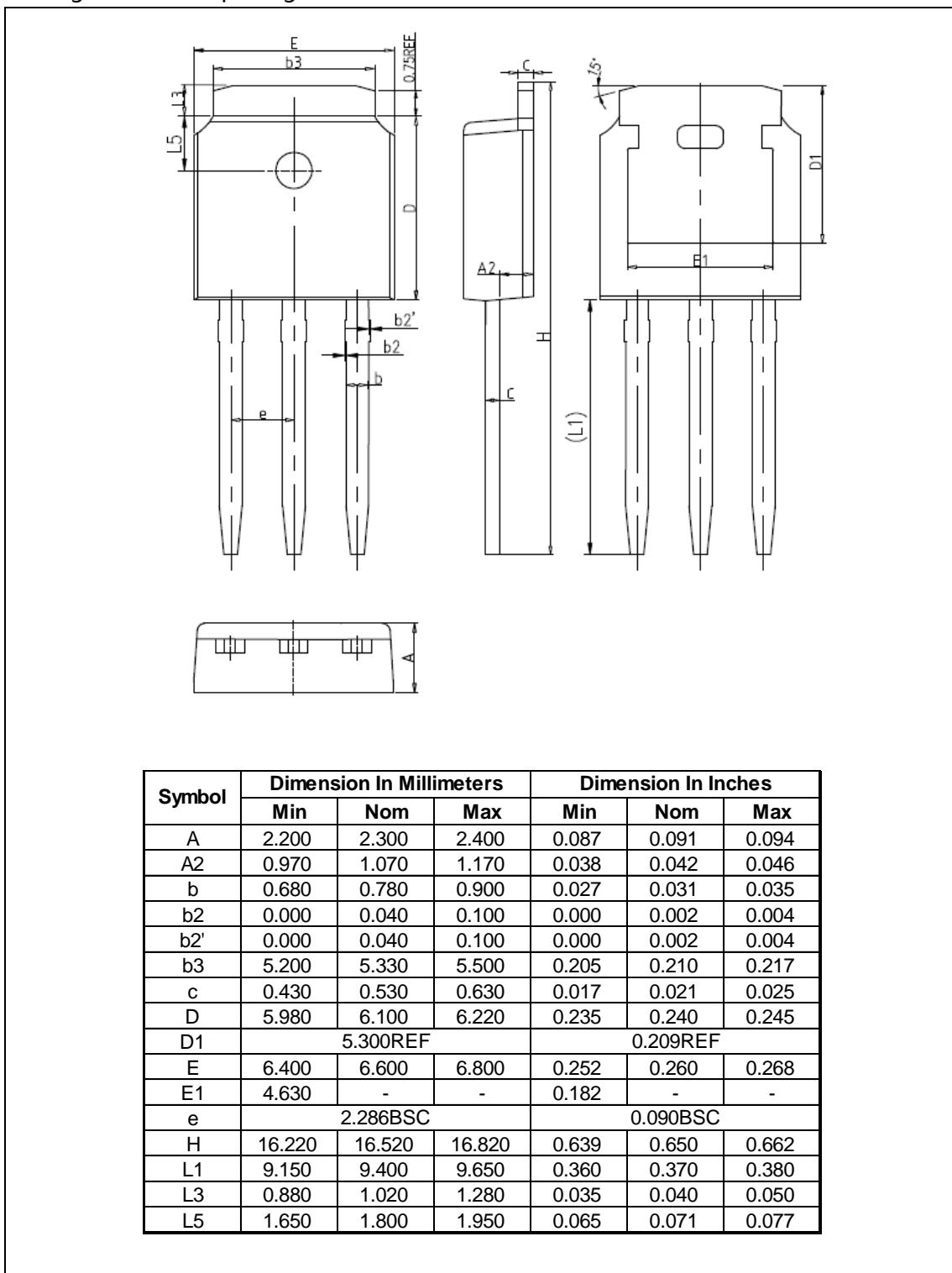


Figure 4, Diode reverse recovery test circuit & waveforms



■ Package Information

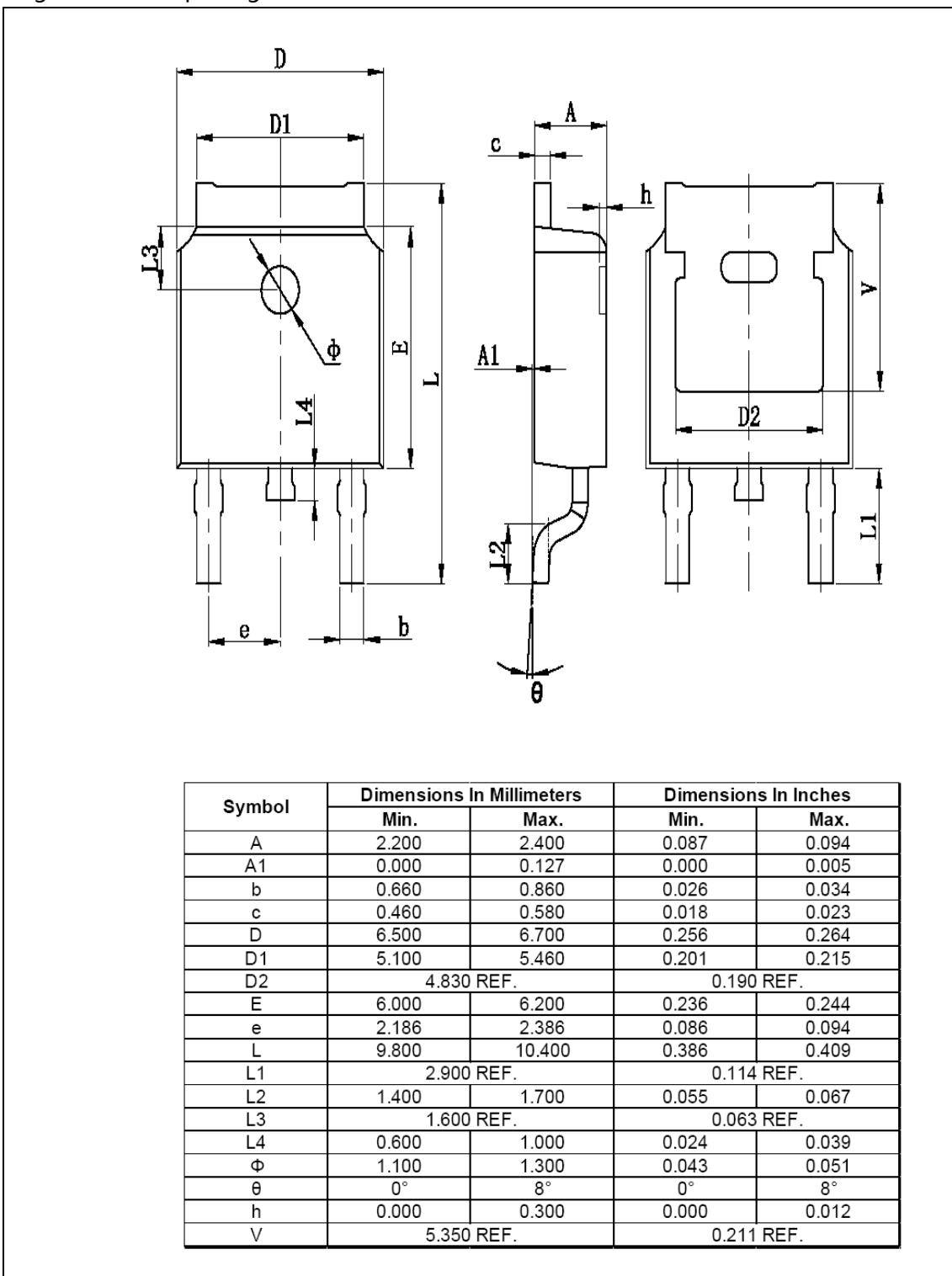
Figure1, TO251 package outline dimension





■ Package Information

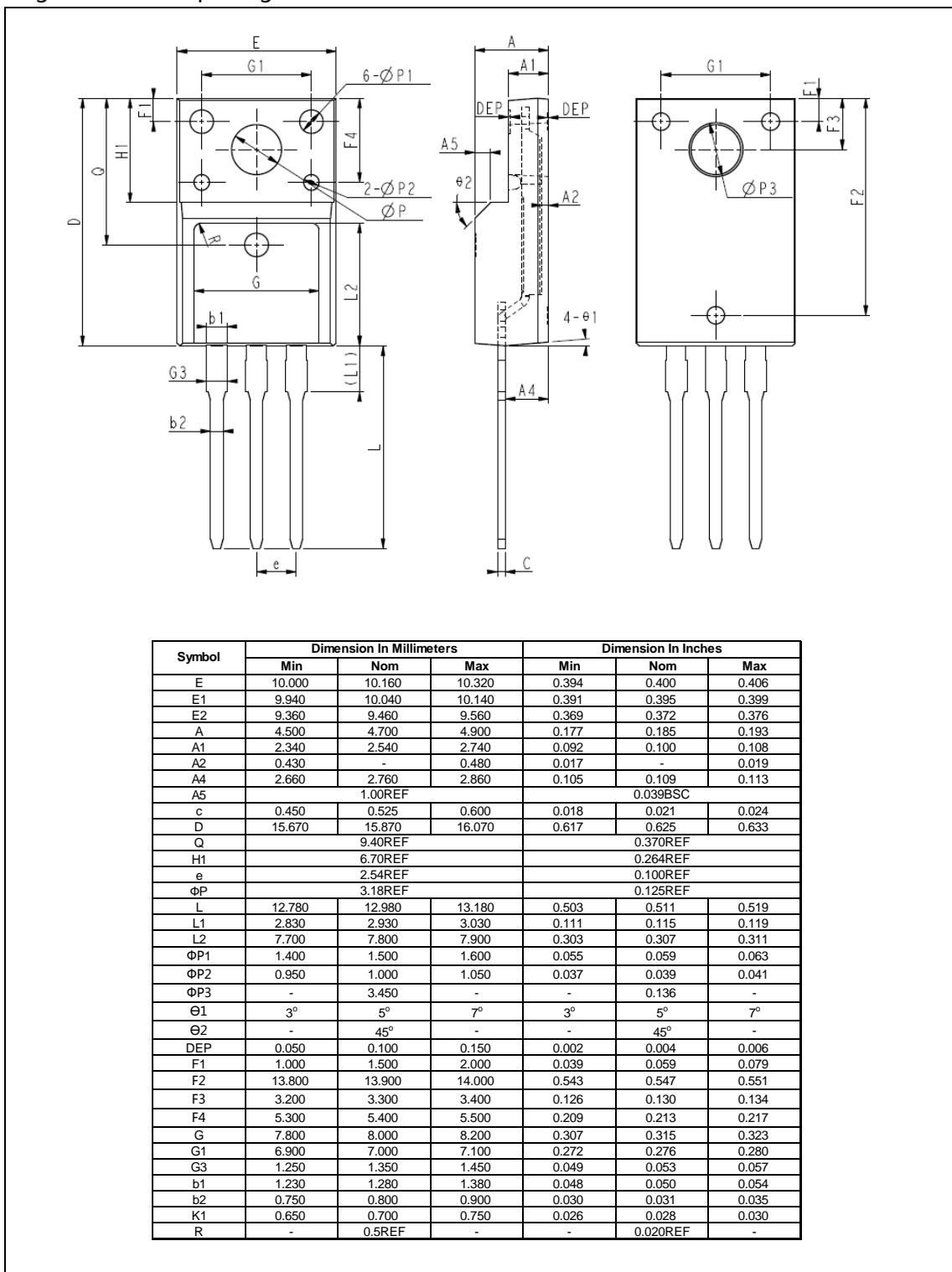
Figure2, TO252 package outline dimension





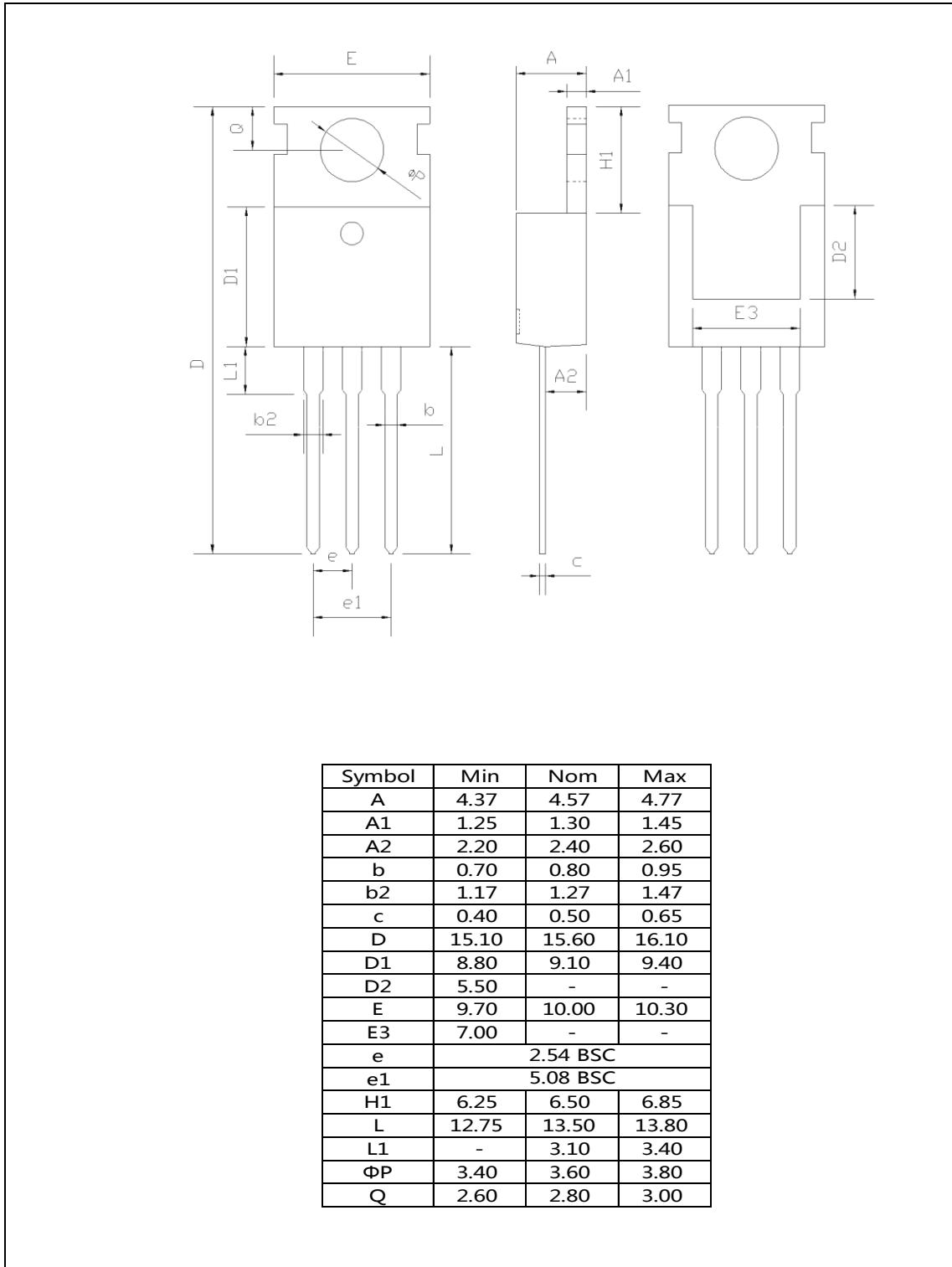
■ Package Information

Figure3, TO220F package outline dimension



■ Package Information

Figure4, TO220 package outline dimension





■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO251	75	66	4950	6	29700
TO252 Option1	75	66	4950	6	29700
TO220F	50	20	1000	6	6000
TO220	50	20	1000	6	6000

Package	Units/Tape	Tapes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO252 Option2	2500	2	5000	5	25000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R2K2A	TO251	yes	yes	no
OSG60R2K2AF	TO251	yes	yes	yes
OSG60R2K2D	TO252	yes	yes	no
OSG60R2K2DF	TO252	yes	yes	yes
OSG60R2K2F	TO220F	yes	yes	no
OSG60R2K2FF	TO220F	yes	yes	yes
OSG60R2K2P	TO220	yes	yes	no
OSG60R2K2PF	TO220	yes	yes	yes